ABSTRACT

A system and method for the fabrication of high reliability capacitors (**1011**), inductors (**1012**), and multi-layer interconnects (**1013**) (including resistors (**1014**)) on various thin film hybrid substrate surfaces (**0501**) is disclosed. The disclosed method first employs a thin metal layer (**0502**) deposited and patterned on the substrate (**0501**). This thin patterned layer (**0502**) is used to provide both lower electrodes for capacitor structures (**0603**) and interconnects (**0604**) between upper electrode components. Next, a dielectric layer (**0705**) is deposited over the thin patterned layer (**0502**) and the dielectric layer (**0705**) is patterned to open contact holes (**0806**) to the thin patterned layer. The upper electrode layers (**0907, 0908, 1009, 1010**) are then deposited and patterned on top of the dielectric (**0705**).